

PATENT ASSIGNMENT COVER SHEET

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EPAS ID: PAT6179888

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
HUAN-CHU HUANG	05/21/2020
JIAGUO LU	05/22/2020
HONG LIN	05/21/2020
JUNYONG LIU	05/22/2020
ZHIXING QI	05/21/2020
MINHUI ZENG	05/22/2020
YANCHAO ZHOU	05/21/2020
JINGWEI LI	05/22/2020
TAO MA	05/22/2020

RECEIVING PARTY DATA

Name:	ETHETA COMMUNICATION TECHNOLOGY (SHENZHEN) CO., LTD
Street Address:	FLOOR 4, INDEPENDENT BUILDING, NO. 6, ZHANGFENG RD.
Internal Address:	ORIENTAL COMMUNITY, SONGGANG ST., BAO'AN DISTRICT
City:	SHENZHEN CITY, GUANGDONG PROVINCE
State/Country:	CHINA
Name:	EAST CHINA RESEARCH INSTITUTE OF MICROELECTRONICS
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Internal Address:	HIGH-TECH DEVELOPMENT ZONE,
City:	HEFEI, ANHUI PROVINCE
State/Country:	CHINA

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	16917503

CORRESPONDENCE DATA

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Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.

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Correspondent Name:	LUCAS & MERCANTI, LLP
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Address Line 4:	NEW YORK, NEW YORK 10004

ATTORNEY DOCKET NUMBER:	4149-02
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NAME OF SUBMITTER:	YUN H. CHOE
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SIGNATURE:	/Yun H. Choe/
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DATE SIGNED:	06/30/2020
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Total Attachments: 3

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ASSIGNMENT OF RIGHTS, TITLE AND INTEREST IN INVENTION

This is an assignment of the following rights, title and interest (check all that apply):

- ☒ *United States of America rights, title and interest in the invention*
- ☒ *Foreign rights, title and interest in the invention*
- ☐ *United States Patent Application Serial No.*
Date of Execution: _____ Date of Filing: _____
- ☐ *United States Provisional Patent Application Serial No.*
- ☐ *United States Patent No(s). _____*
- ☐ **International (PCT) Patent Application Serial No**
- ☐ *Other (specify): _____*

Title of the Invention:

INTEGRATION MODULE SYSTEM OF MILLIMETER-WAVE AND NON-MILLIMETER-WAVE ANTENNAS AND ELECTRONIC APPARATUS

Inventors (assignors):

Name	Address
HUANG, Huan-Chu	13F, No. 33, Nanchang Road, Luju District, Taoyuan City, Taiwan 338
LU, Jiaguo	No. 19, Hehuan Road, High-Tech Development Zone, Hefei, Anhui Province, China
LIN, Hong	Floor 4, Independent Building, No. 6, Zhangfeng Road, Oriental Community, Songgang Street, Bao'an District, Shenzhen City, Guangdong Province, China
LIU, Junyong	No. 19, Hehuan Road, High-Tech Development Zone, Hefei, Anhui Province, China
QI, Zhixing	Floor 4, Independent Building, No. 6, Zhangfeng Road, Oriental Community, Songgang Street, Bao'an District, Shenzhen City, Guangdong Province, China
ZENG, Minhui	No. 19, Hehuan Road, High-Tech Development Zone, Hefei, Anhui Province, China
ZHOU, Yanchao	Floor 4, Independent Building, No. 6, Zhangfeng Road, Oriental Community, Songgang Street, Bao'an District, Shenzhen City, Guangdong Province, China
LI, Jingwei	No. 19, Hehuan Road, High-Tech Development Zone, Hefei, Anhui Province, China

MA, Tao	No. 19, Hehuan Road, High-Tech Development Zone, Hefei, Anhui Province, China
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Assignee:

Name	Address
ETHETA COMMUNICATION TECHNOLOGY (SHENZHEN) CO., LTD	Floor 4, Independent Building, No. 6, Zhangfeng Road, Oriental Community, Songgang Street, Bao'an District, Shenzhen City, Guangdong Province, China
EAST CHINA RESEARCH INSTITUTE OF MICROELECTRONICS	No. 19, Hehuan Road, High-Tech Development Zone, Hefei, Anhui Province, China

WHEREAS, we, the above-identified Inventors, have invented certain new and useful improvements in the Invention identified above and described in the above-identified patent application(s) and/or patent(s) (hereinafter referred to as "Invention");

And, whereas we desire to assign our above-identified rights, title and interest in the Invention to the above-identified Assignee;

NOW, this indenture witnesseth, that in consideration of the sum of ONE DOLLAR (\$1.00), the receipt of which is hereby acknowledged, and for other good and valuable consideration;

We hereby assign, sell and transfer our above-identified rights, title and interest in said Invention, said application(s) as identified above, including any divisions, continuations, and continuations-in-part thereof, and in and to any and all Letters Patent of the United States, and countries foreign thereto, which may be granted for said Invention, and in and to any and all reissues and reexaminations thereof, which may be granted or have granted for said Invention, and in and to any and all priority rights, Convention rights, and other benefits accruing or to accrue to us with respect to the filing of applications for patents or securing of patents in the United States and countries foreign thereto, unto said Assignee;

And we hereby authorize and request the Commissioner of Patents and Trademarks to issue any United States Letters Patent which may issue for said Invention to said Assignee, as assignee of the whole right, title and interest thereto;

And we further agree to sign and execute all necessary and lawful future documents, including applications for foreign patents, for filing divisions, continuations and continuation-in-part of said application for patent and/or for obtaining any reissue or reissues of any Letters Patent which may be granted for my aforesaid Invention, as the Assignee or its Designee(s) may from time to time require and prepare at its own expense.

The undersigned hereby grant(s) the firm of LUCAS & MERCANTI, LLP, located at 30 Broad Street, New York, New York, 10004, the power to insert on this assignment any further identification which may be necessary or desirable in order to comply with the rules of the United States Patent Office for recordation of this document.

Inventors' Signatures:

Name	Signature	Date
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Docket No.

HUANG, Huan-Chu	Huang, Huan-Chu 黃煥衢	2020/05/21
LU, Jiaguo	Lu Jiaguo 王加國	2020-5-22
LIN, Hong	Lin Hong 林虹	2020-5-21
LIU, Junyong	Liu Junyong 刘俊永	2020-5-22
QI, Zhixing	QI, Zhixing 秦知行	2020-5-21
ZENG, Minhui	Zeng Minhui 曾敏慧	2020-5-22
ZHOU, Yanchao	ZHOU, Yanchao 周彦超	2020-5-21
LI, Jingwei	Li Jingwei 李靖巍	2020-5-22
MA, Tao	Ma Tao 马涛	2020-5-22

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